- Low Output Skew, Low Pulse Skew for Clock-Distribution and Clock-Generation Applications
- TTL-Compatible Inputs and Outputs
- Distributes One Clock Input to Eight Outputs
- Distributed V<sub>CC</sub> and Ground Pins Reduce Switching Noise
- High-Drive Outputs (-48-mA I<sub>OH</sub>, 48-mA I<sub>OI</sub> )
- State-of-the-Art EPIC-IIB™ BiCMOS Design Significantly Reduces Power Dissipation
- Package Options Include Plastic Small-Outline (DW) and Shrink

#### **DW PACKAGE** (TOP VIEW) 20 VCC Vcc [ 1G [ 19 1Y1 2 2G [] 3 18 ¶ 1Y2 17 GND ΑП Р0 П 16 1Y3 Р1 Г 15 1Y4 6 14 GND $v_{cc}$ 2Y4 **1** 8 13 2Y1 12 2Y2 2Y3 I 9 GND **1** 10 11 | GND

### description

The CDC340 is a high-performance clock-driver circuit that distributes one (A) input signal to eight (Y) outputs with minimum skew for clock distribution. Through the use of the control pins (1G and 2G), the outputs can be placed in a high state regardless of the A input.

The propagation delays are adjusted at the factory using the P0 and P1 pins. These pins are not intended for customer use and should be strapped to GND.

The CDC340 is characterized for operation from 0°C to 70°C.

**FUNCTION TABLE** 

	INPUTS		OUTPUTS				
1G	2G	Α	1Y1-1Y4	2Y1-2Y4			
Х	Х	L	Н	Н			
L	L	Н	Н	Н			
L	Н	Н	Н	L			
Н	L	Н	L	Н			
Н	Н	Н	L	L			

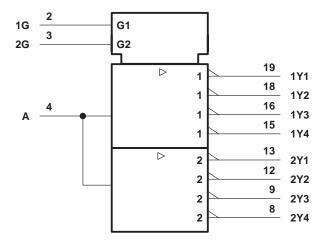


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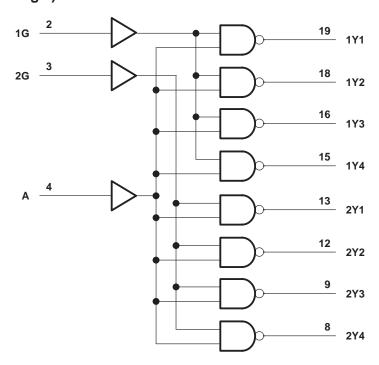


### logic symbol†



<sup>&</sup>lt;sup>†</sup> This symbol is in accordance with ANSI/IEEE Std 91-1984 and IEC Publication 617-12.

### logic diagram (positive logic)





### absolute maximum ratings over operating free-air temperature range (unless otherwise noted)†

NOTES: 1. The input and output negative-voltage ratings may be exceeded if the input and output clamp-current ratings are observed.

### recommended operating conditions (see Note 3)

			MIN	MAX	UNIT
Vcc	Supply voltage	4.75	5.25	V	
VIH	High-level input voltage		2		V
V <sub>IL</sub>	Low-level input voltage			0.8	V
VI	Input voltage				V
loh	High-level output current			-48	mA
l <sub>OL</sub>	Low-level output current			48	mA
f	langet along fraguency	One output back loaded		80	MHz
fclock	Input clock frequency	Both output banks loaded		40	IVITIZ
TA	Operating free-air temperature		0	70	°C

NOTE 3: Unused inputs must be held high or low to prevent them from floating.

# electrical characteristics over recommended operating free-air temperature range (unless otherwise noted)

PARAMETER	TEST CONDITIONS			T <sub>A</sub> = 25°C			MIN	MAX	UNIT
FARAMETER	'	EST CONDITIONS		MIN	TYP <sup>‡</sup>	MAX	IVIIIN	WAX	UNIT
VIK	$V_{CC} = 4.75 \text{ V},$	I <sub>I</sub> = -18 mA				-1.2		-1.2	V
	$V_{CC} = 4.75 V$ ,	$I_{OH} = -3 \text{ mA}$		2.5			2.5		
$V_{OH}$	$V_{CC} = 5 V$ ,	$I_{OH} = -3 \text{ mA}$		3			3		V
	$V_{CC} = 4.75 V$ ,	$I_{OH} = -48 \text{ mA}$		2			2		
V <sub>OL</sub>	$V_{CC} = 4.75 V$ ,	$I_{OL} = 48 \text{ mA}$						0.5	V
lį	$V_{CC} = 5.25 \text{ V},$	$V_I = V_{CC}$ or GND				±1		±1	μΑ
ΙΟ <sup>§</sup>	$V_{CC} = 5.25 \text{ V},$	V <sub>O</sub> = 2.5 V		-50	-100	-200	-50	-200	mA
loo	V <sub>CC</sub> = 5.25 V,	l <sub>O</sub> = 0,	Outputs high		2			3.5	mA
lcc	$V_I = V_{CC}$ or GND	-	Outputs low		24			33	IIIA
Ci	V <sub>I</sub> = 2.5 V or 0.5 V	_	_		3			·	pF

<sup>‡</sup> All typical values are at  $V_{CC} = 5 \text{ V}$ .



<sup>†</sup> Stresses beyond those listed under "absolute maximum ratings" may cause permanent damage to the device. These are stress ratings only and functional operation of the device at these or any other conditions beyond those indicated under "recommended operating conditions" is not implied. Exposure to absolute-maximum-rated conditions for extended periods may affect device reliability.

The maximum package power dissipation is calculated using a junction temperature of 150°C and a board trace length of 750 mils.
 For more information, refer to the Package Thermal Considerations Application Note in the ABT Advanced BiCMOS Technology Data Book, literature number SCBD002.

<sup>§</sup> No more than one output should be tested at a time, and the duration of the test should not exceed one second.

## switching characteristics, $C_L = 50 \text{ pF}$ (see Figure 1 and Figure 2)

PARAMETER		FROM (INPUT)	TO (OUTPUT)	V <sub>CC</sub> = 5 V, T <sub>A</sub> = 25°C			V <sub>CC</sub> = 4.75 T <sub>A</sub> = 0°	UNIT	
		(INPUT)	(001701)	MIN	TYP	MAX	MIN	MAX	
tPLH	Propagation delay time, low-to-high level	Α	V	3.4		4.5	3	4.8	ns
<sup>t</sup> PHL	Propagation delay time, high-to-low level	^	'	3.2		4.3	2.8	4.7	115
<sup>t</sup> PLH	Propagation delay time, low-to-high level	G	V	2		3.8	2	4	no
t <sub>PHL</sub>	Propagation delay time, high-to-low level	G	ī	2		3.8	2	4	ns
tsk(o)	Skew time, output				0.3	0.5		0.6	
tsk(p)	Skew time, pulse	Α	Υ		0.6	0.8		0.9	ns
tsk(pr)	Skew time, process					1.1		1.1	
t <sub>r</sub>	Rise time	А	Υ					1.5	ns
tf	Fall time	А	Y					1.5	ns

## $t_{\mbox{\scriptsize pd}}$ performance information relative to $V_{\mbox{\scriptsize CC}}$ and temperature variation (see Note 4)

	PARAMETER	∆ change
∆t <sub>PLH(TA)</sub> †	Temperature drift of t <sub>PLH</sub> from 0°C to 70°C	−53 ps/10°C
∆t <sub>PHL(TA)</sub> †	Temperature drift of t <sub>PHL</sub> from 0°C to 70°C	−58 ps/10°C
∆tPLH(VCC) <sup>‡</sup>	V <sub>CC</sub> drift of t <sub>PLH</sub> from 4.75 V to 5.25 V	43 ps/100 mV
∆tPHL(VCC) <sup>‡</sup>	V <sub>CC</sub> drift of t <sub>PHL</sub> from 4.75 V to 5.25 V	-33 ps/100 mV

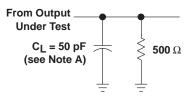
<sup>†</sup> Virtually independent of V<sub>CC</sub>

NOTE 4: The data extracted is from a wide range of characterization material.

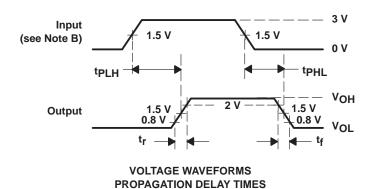


<sup>‡</sup> Virtually independent of temperature

### PARAMETER MEASUREMENT INFORMATION



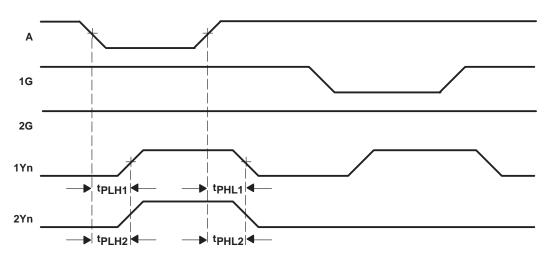
**LOAD CIRCUIT** 



NOTES: A.  $C_L$  includes probe and jig capacitance.

B. All input pulses are supplied by generators having the following characteristics: PRR  $\leq$  10 MHz,  $Z_O = 50 \Omega$ ,  $t_f \leq$  2.5 ns,  $t_f \leq$  2.5 ns.

Figure 1. Load Circuit and Voltage Waveforms



NOTES: A. Output skew,  $t_{Sk(0)}$ , is calculated as the greater of:

- The difference between the fastest and slowest of tp<sub>LHn</sub> (n = 1, 2)
  The difference between the fastest and slowest of tp<sub>HLn</sub> (n = 1, 2)
- B. Pulse skew,  $t_{Sk(p)}$ , is calculated as the greater of  $|t_{PLHn} t_{PHLn}|$  (n = 1, 2).
- C. Process skew,  $t_{sk(pr)}$ , is calculated as the greater of:
  - The difference bétween the fastest and slowest of tpLHn (n = 1, 2) across multiple devices under identical operating conditions
  - The difference between the fastest and slowest of tpHLn (n = 1, 2) across multiple devices under identical operating conditions

Figure 2. Waveforms for Calculation of  $t_{sk(o)}$ ,  $t_{sk(p)}$ ,  $t_{sk(pr)}$ 

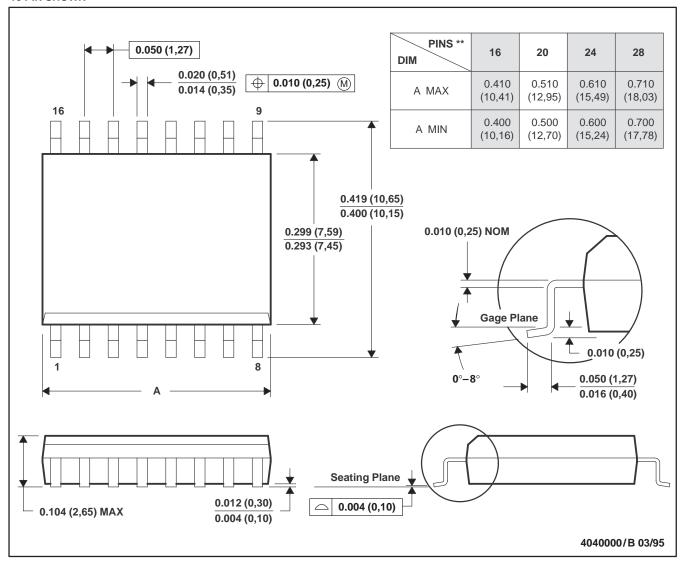


### **MECHANICAL INFORMATION**

### DW (R-PDSO-G\*\*)

### PLASTIC SMALL-OUTLINE PACKAGE

**16 PIN SHOWN** 



- NOTES: A. All linear dimensions are in inches (millimeters).
  - B. This drawing is subject to change without notice.
  - C. Body dimensions do not include mold flash or protrusion not to exceed 0.006 (0,15).
  - D. Falls within JEDEC MS-013



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